Low-power 2-input NAND gate (open drain) Rev. 8 — 7 February 2022

**Product data sheet** 

### 1. General description

The 74AUP1G38 is a single 2-input NAND gate with open-drain output. Schmitt-trigger action at all inputs makes the circuit tolerant of slower input rise and fall times. This device ensures very low static and dynamic power consumption across the entire V<sub>CC</sub> range from 0.8 V to 3.6 V. This device is fully specified for partial power down applications using I<sub>OFF</sub>. The I<sub>OFF</sub> circuitry disables the output, preventing the potentially damaging backflow current through the device when it is powered down.

### 2. Features and benefits

- Wide supply voltage range from 0.8 V to 3.6 V
- CMOS low power dissipation
- High noise immunity
- Complies with JEDEC standards:
  - JESD8-12 (0.8 V to 1.3 V)
  - JESD8-11 (0.9 V to 1.65 V)
  - JESD8-7 (1.65 V to 1.95 V)
  - JESD8-5 (2.3 V to 2.7 V)
  - JESD8C (2.7 V to 3.6 V)
- ESD protection:
  - HBM JESD22-A114F Class 3A exceeds 5000 V
  - MM JESD22-A115-A exceeds 200 V
  - CDM JESD22-C101E exceeds 1000 V
- Low static power consumption; I<sub>CC</sub> = 0.9 μA (maximum)
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Overvoltage tolerant inputs to 3.6 V
- Low noise overshoot and undershoot < 10 % of V<sub>CC</sub>
- I<sub>OFF</sub> circuitry provides partial Power-down mode operation
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

# ne<mark>x</mark>peria

# 3. Ordering information

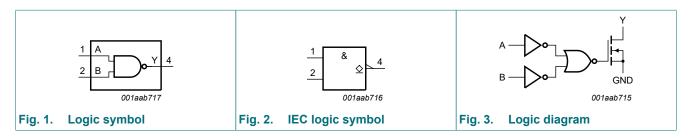
Type number	Package	Package						
	Temperature range	Name	Description	Version				
74AUP1G38GW	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1				
74AUP1G38GM	-40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886				
74AUP1G38GN	-40 °C to +125 °C	5 °C XSON6 extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm						
74AUP1G38GS	-40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202				
74AUP1G38GX	-40 °C to +125 °C	X2SON5	plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 × 0.8 × 0.35 mm	SOT1226				

### 4. Marking

Table 2. Marking	
Type number	Marking code[1]
74AUP1G38GW	aB
74AUP1G38GM	aB
74AUP1G38GN	aB
74AUP1G38GS	aB
74AUP1G38GX	aB

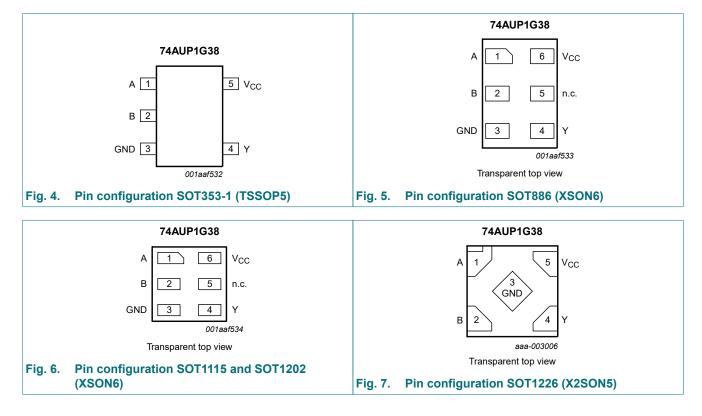
[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

# 5. Functional diagram



### 6. Pinning information

6.1. Pinning



### 6.2. Pin description

Table 3. Pin descriptionSymbol	Pin	Pin		
	TSSOP5 and X2SON5	XSON6		
A	1	1	data input	
В	2	2	data input	
GND	3	3	ground (0 V)	
Y	4	4	data output	
n.c.	-	5	not connected	
V <sub>CC</sub>	5	6	supply voltage	

### 7. Functional description

#### Table 4. Function table

H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF state.

Input		Output
Α	В	Y
L	L	Z
L	Н	Z
н	L	Z
Н	Н	L

### 8. Limiting values

#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>CC</sub>	supply voltage			-0.5	+4.6	V
I <sub>IK</sub>	input clamping current	V <sub>1</sub> < 0 V		-50	-	mA
VI	input voltage		[1]	-0.5	+4.6	V
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < 0 V		-50	-	mA
Vo	output voltage	Active mode and Power-down mode	[1]	-0.5	+4.6	V
I <sub>O</sub>	output current	$V_{O} = 0 V$ to $V_{CC}$		-	+20	mA
I <sub>CC</sub>	supply current			-	+50	mA
I <sub>GND</sub>	ground current			-50	-	mA
T <sub>stg</sub>	storage temperature			-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C	[2]	-	250	mW

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SOT353-1 (TSSOP5) package: P<sub>tot</sub> derates linearly with 3.3 mW/K above 74 °C.

For SOT886 (XSON6) package: P<sub>tot</sub> derates linearly with 3.3 mW/K above 74 °C.

For SOT1115 (XSON6) package: P<sub>tot</sub> derates linearly with 3.2 mW/K above 71 °C.

For SOT1202 (XSON6) package: Ptot derates linearly with 3.3 mW/K above 74 °C.

For SOT1226 (X2SON5) package: Ptot derates linearly with 3.0 mW/K above 67 °C.

### 9. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		0.8	3.6	V
VI	input voltage		0	3.6	V
Vo	output voltage	Active mode and Power-down mode	0	3.6	V
T <sub>amb</sub>	ambient temperature		-40	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 0.8 V to 3.6 V	0	200	ns/V

# **10. Static characteristics**

### Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
T <sub>amb</sub> = 2	5 °C	Image: space of the system of the				
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 0.8 V	0.70 × V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	$0.65 \times V_{CC}$	-	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	$0.30 \times V_{CC}$	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	$0.35 \times V_{CC}$	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V
V <sub>OL</sub>	LOW-level output voltage	$V_{I} = V_{IH} \text{ or } V_{IL}$				
		$I_{O}$ = 20 µA; $V_{CC}$ = 0.8 V to 3.6 V	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	$0.3 \times V_{CC}$	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.31	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.31	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.31	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.44	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.31	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.44	V
l <sub>l</sub>	input leakage current	$V_I$ = GND to 3.6 V; $V_{CC}$ = 0 V to 3.6 V	-	-	±0.1	μA
I <sub>OZ</sub>	OFF-state output current		-	-	±0.1	μA
I <sub>OFF</sub>	power-off leakage current	$V_1$ or $V_0$ = 0 V to 3.6 V; $V_{CC}$ = 0 V	-	-	±0.2	μA
Δl <sub>OFF</sub>	additional power-off leakage current	$V_1$ or $V_0$ = 0 V to 3.6 V; $V_{CC}$ = 0 V to 0.2 V	-	-	±0.2	μA
I <sub>CC</sub>	supply current	$V_{I} = GND \text{ or } V_{CC}; I_{O} = 0 \text{ A};$ $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.5	μA
Δl <sub>CC</sub>	additional supply current	$V_{I} = V_{CC} - 0.6 \text{ V}; I_{O} = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$	-	-	40	μA
CI	input capacitance	$V_{CC}$ = 0 V to 3.6 V; V <sub>I</sub> = GND or V <sub>CC</sub>	-	0.8	-	pF
Co	output capacitance	output enabled; $V_0$ = GND; $V_{CC}$ = 0 V	-	1.7	-	pF
		output disabled; $V_0$ = GND; $V_{CC}$ = 0 V	-	1.1	-	pF

Symbol	Parameter	Conditions	Min	Тур	Мах	Unit
T <sub>amb</sub> = -4	40 °C to +85 °C	1				
VIH	HIGH-level input voltage	V <sub>CC</sub> = 0.8 V	0.70 × V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	$0.65 \times V_{CC}$	-	-	V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	$0.30 \times V_{CC}$	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	$0.35 \times V_{CC}$	V
		$V_{CC}$ = 2.3 V to 2.7 V	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V
V <sub>OL</sub>	LOW-level output voltage	$V_{I} = V_{IH} \text{ or } V_{IL}$				
		$I_{O}$ = 20 µA; $V_{CC}$ = 0.8 V to 3.6 V	-	-	0.1	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	$0.3 \times V_{CC}$	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.37	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.35	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.33	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.45	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.33	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.45	V
l <sub>l</sub>	input leakage current	$V_I$ = GND to 3.6 V; $V_{CC}$ = 0 V to 3.6 V	-	-	±0.5	μA
l <sub>OZ</sub>	OFF-state output current	$V_{I} = V_{IH}$ or $V_{IL}$ (and at least one input LOW); $V_{O} = 0$ V to 3.6 V; $V_{CC} = 0$ V to 3.6 V	-	-	±0.5	μA
I <sub>OFF</sub>	power-off leakage current	$V_{I}$ or $V_{O}$ = 0 V to 3.6 V; $V_{CC}$ = 0 V	-	-	±0.5	μA
ΔI <sub>OFF</sub>	additional power-off leakage current	$V_1$ or $V_0$ = 0 V to 3.6 V; $V_{CC}$ = 0 V to 0.2 V	-	-	±0.6	μA
I <sub>CC</sub>	supply current	$V_{I} = GND \text{ or } V_{CC}; I_{O} = 0 \text{ A};$ $V_{CC} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.9	μA
ΔI <sub>CC</sub>	additional supply current	$V_{I} = V_{CC} - 0.6 \text{ V}; I_{O} = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$	-	-	50	μA

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
T <sub>amb</sub> = -	40 °C to +125 °C				-	
VIH	HIGH-level input voltage	V <sub>CC</sub> = 0.8 V	0.75 × V <sub>CC</sub>	-	-	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	$0.70 \times V_{CC}$	-	-	V
		$V_{CC}$ = 2.3 V to 2.7 V	1.6	-	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 0.8 V	-	-	$0.25 \times V_{CC}$	V
		V <sub>CC</sub> = 0.9 V to 1.95 V	-	-	$0.30 \times V_{CC}$	V
		$V_{CC}$ = 2.3 V to 2.7 V	-	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	V
V <sub>OL</sub>	LOW-level output voltage	$V_{I} = V_{IH} \text{ or } V_{IL}$				
		$I_{O}$ = 20 µA; $V_{CC}$ = 0.8 V to 3.6 V	-	-	0.11	V
		I <sub>O</sub> = 1.1 mA; V <sub>CC</sub> = 1.1 V	-	-	$0.33 \times V_{CC}$	V
		I <sub>O</sub> = 1.7 mA; V <sub>CC</sub> = 1.4 V	-	-	0.41	V
		I <sub>O</sub> = 1.9 mA; V <sub>CC</sub> = 1.65 V	-	-	0.39	V
		I <sub>O</sub> = 2.3 mA; V <sub>CC</sub> = 2.3 V	-	-	0.36	V
		I <sub>O</sub> = 3.1 mA; V <sub>CC</sub> = 2.3 V	-	-	0.50	V
		I <sub>O</sub> = 2.7 mA; V <sub>CC</sub> = 3.0 V	-	-	0.36	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V	-	-	0.50	V
I <sub>I</sub>	input leakage current	$V_I$ = GND to 3.6 V; $V_{CC}$ = 0 V to 3.6 V	-	-	±0.75	μA
I <sub>OZ</sub>	OFF-state output current	$V_I = V_{IH}$ or $V_{IL}$ (and at least one input LOW); $V_O = 0$ V to 3.6 V; $V_{CC} = 0$ V to 3.6 V	-	-	±0.75	μA
I <sub>OFF</sub>	power-off leakage current	$V_{1} \text{ or } V_{0} = 0 \text{ V to } 3.6 \text{ V; } V_{CC} = 0 \text{ V}$	-	-	±0.75	μA
ΔI <sub>OFF</sub>	additional power-off leakage current	$V_{I}$ or $V_{O}$ = 0 V to 3.6 V; $V_{CC}$ = 0 V to 0.2 V	-	-	±0.75	μA
I <sub>CC</sub>	supply current	$V_1$ = GND or $V_{CC}$ ; $I_0$ = 0 A; $V_{CC}$ = 0.8 V to 3.6 V	-	-	1.4	μA
ΔI <sub>CC</sub>	additional supply current	$V_{I} = V_{CC} - 0.6 \text{ V}; I_{O} = 0 \text{ A}; V_{CC} = 3.3 \text{ V}$	-	-	75	μA
	1		1		1	1

# **11. Dynamic characteristics**

### Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V; for test circuit see Fig. 9

Symbol	Parameter	Conditions		25 °C		-40 °C t	o +85 °C	-40 °C to	o +125 °C	Unit
			Min	Typ[1]	Мах	Min	Max	Min	Max	
C <sub>L</sub> = 5 p	F	· · · · · · · · · · · · · · · · · · ·								
t <sub>pd</sub>		A or B to Y; see <u>Fig. 8</u> [2]								
	delay	V <sub>CC</sub> = 0.8 V	-	13.5	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	1.9	4.6	10.4	1.8	11.4	1.8	12.6	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	1.5	3.3	6.5	1.4	7.4	1.4	8.2	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.2	2.9	5.1	1.1	5.9	1.1	6.5	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.0	2.2	3.8	0.9	4.5	0.9	4.9	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	0.9	2.3	4.0	0.8	4.5	0.8	4.9	ns
C <sub>L</sub> = 10	pF								Ż	
t <sub>pd</sub>	propagation	A or B to Y; see Fig. 8 [2]								
	delay	V <sub>CC</sub> = 0.8 V	-	16.3	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	2.3	5.6	12.3	2.1	13.7	2.1	15.1	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	1.8	4.1	7.6	1.7	8.8	1.7	9.7	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.6	3.8	6.1	1.4	7.1	1.4	7.8	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.4	2.9	4.6	1.2	5.4	1.2	5.9	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.3	3.2	5.7	1.1	6.4	1.1	7.0	ns
C <sub>L</sub> = 15	pF									
t <sub>pd</sub>		A or B to Y; see Fig. 8 [2]								
	delay	V <sub>CC</sub> = 0.8 V	-	19.0	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	2.6	6.6	14.2	2.4	15.8	2.4	17.4	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	2.1	4.8	8.7	1.9	10.1	1.9	11.1	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	1.9	4.6	7.6	1.7	8.5	1.7	9.3	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.6	3.6	5.6	1.5	6.3	1.5	6.9	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	1.6	4.1	7.5	1.4	8.3	1.4	9.1	ns
C <sub>L</sub> = 30	pF									
t <sub>pd</sub>		A or B to Y; see Fig. 8 [2]								
	delay	V <sub>CC</sub> = 0.8 V	-	27.0	-	-	-	-	-	ns
		V <sub>CC</sub> = 1.1 V to 1.3 V	3.6	9.5	19.5	3.2	21.8	3.2	24.0	ns
		V <sub>CC</sub> = 1.4 V to 1.6 V	2.9	7.0	11.5	2.6	13.6	2.6	15.0	ns
		V <sub>CC</sub> = 1.65 V to 1.95 V	2.6	7.0	12.1	2.3	13.3	2.3	14.6	ns
		V <sub>CC</sub> = 2.3 V to 2.7 V	2.4	5.4	8.9	2.1	9.9	2.1	10.9	ns
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.3	6.5	12.7	2.1	13.9	2.1	15.3	ns

### Low-power 2-input NAND gate (open drain)

Symbol	Parameter	Conditions		25 °C		-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ[1]	Max	Min	Max	Min	Max	
C <sub>L</sub> = 5 p	F, 10 pF, 15 p	F and 30 pF					•		-	
-10	dissipation	$f_i = 1 \text{ MHz};$ [3] V <sub>I</sub> = GND to V <sub>CC</sub>								
	capacitance	V <sub>CC</sub> = 0.8 V	-	0.6	-	-	-	-	-	pF
		V <sub>CC</sub> = 1.1 V to 1.3 V	-	0.7	-	-	-	-	-	pF
		V <sub>CC</sub> = 1.4 V to 1.6 V	-	0.8	-	-	-	-	-	pF
		V <sub>CC</sub> = 1.65 V to 1.95 V	-	0.9	-	-	-	-	-	pF
		V <sub>CC</sub> = 2.3 V to 2.7 V	-	1.1	-	-	-	-	-	pF
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	1.4	-	-	-	-	-	pF

[1] All typical values are measured at nominal  $V_{CC}$ .

[2]  $t_{pd}$  is the same as  $t_{PZL}$  and  $t_{PLZ}$ .

[3]  $\dot{C}_{PD}$  is used to determine the dynamic power dissipation (P<sub>D</sub> in  $\mu$ W).

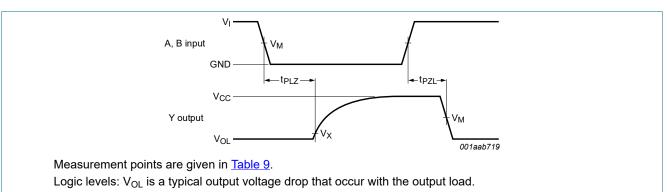
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N$  where:

f<sub>i</sub> = input frequency in MHz;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching.

### 11.1. Waveforms and test circuit

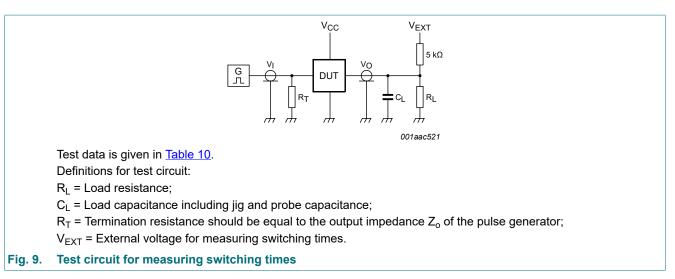


#### Fig. 8. The data input (A or B) to output (Y) propagation delays

#### **Table 9. Measurement points**

Supply voltage	Input			Output	Output		
V <sub>cc</sub>	V <sub>M</sub>	VI	t <sub>r</sub> = t <sub>f</sub>	V <sub>M</sub>	V <sub>X</sub>		
0.8 V to 1.6 V	$0.5 \times V_{CC}$	V <sub>CC</sub>	≤ 3.0 ns	0.5 × V <sub>CC</sub>	V <sub>OL</sub> + 0.1 V		
1.65 V to 2.7 V	$0.5 \times V_{CC}$	V <sub>CC</sub>	≤ 3.0 ns	0.5 × V <sub>CC</sub>	V <sub>OL</sub> + 0.15 V		
3.0 V to 3.6 V	$0.5 \times V_{CC}$	V <sub>CC</sub>	≤ 3.0 ns	0.5 × V <sub>CC</sub>	V <sub>OL</sub> + 0.3 V		

### Low-power 2-input NAND gate (open drain)



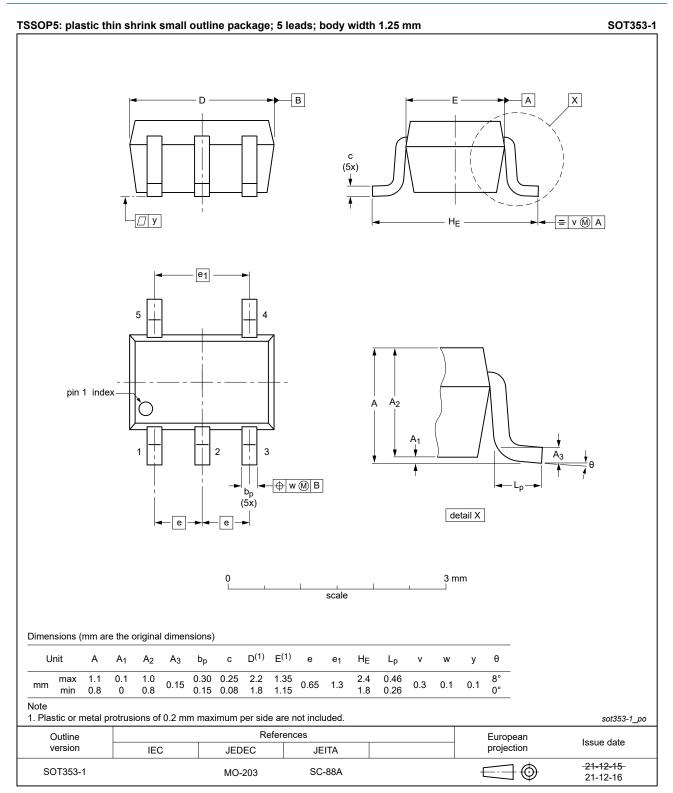
#### Table 10. Test data

Supply voltage	Load	V <sub>EXT</sub>			
V <sub>cc</sub>	CL	R <sub>L</sub> [1]	t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PZH</sub> , t <sub>PHZ</sub>	t <sub>PZL</sub> , t <sub>PLZ</sub>
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF and 30 pF	5 k $\Omega$ or 1 M $\Omega$	open	GND	$2 \times V_{CC}$

[1] For measuring enable and disable times  $R_L = 5 k\Omega$ .

For measuring propagation delays, setup and hold times and pulse width  $R_L$  = 1  $M\Omega.$ 

### 12. Package outline



### Fig. 10. Package outline SOT353-1 (TSSOP5)

### Low-power 2-input NAND gate (open drain)

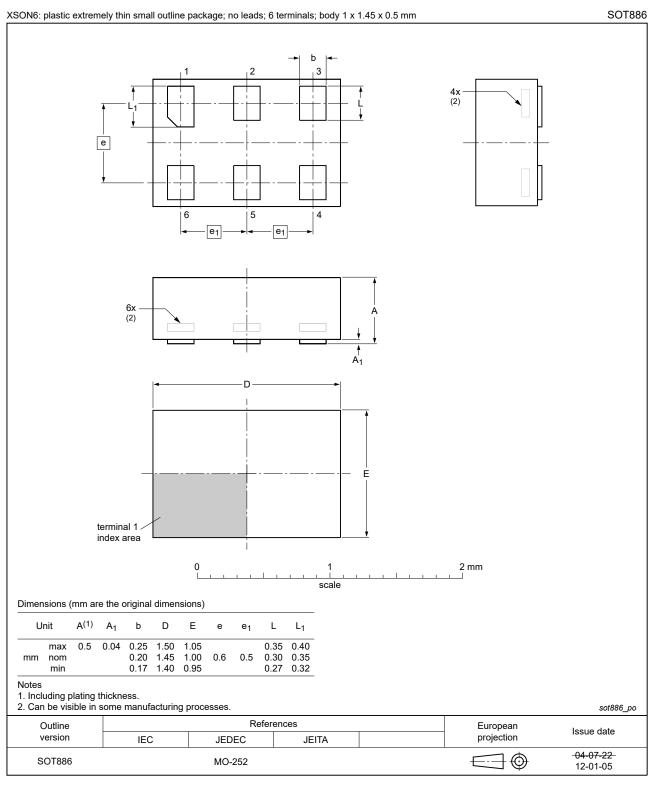
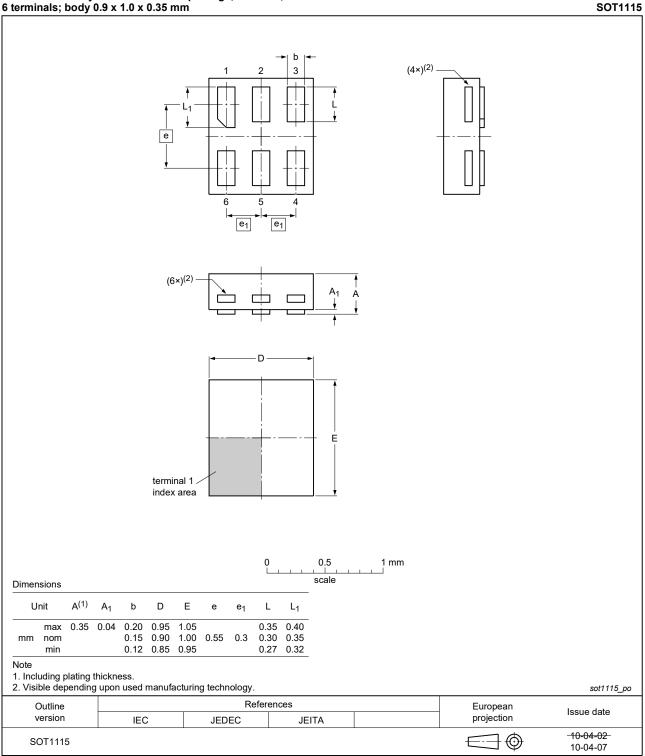


Fig. 11. Package outline SOT886 (XSON6)

#### Low-power 2-input NAND gate (open drain)

#### XSON6: extremely thin small outline package; no leads; 6 terminals; body 0.9 x 1.0 x 0.35 mm





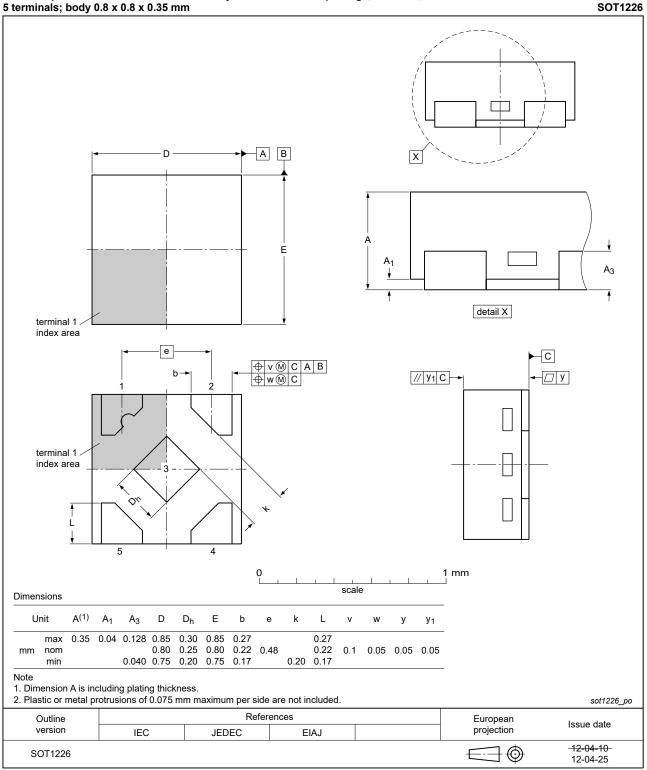
### Low-power 2-input NAND gate (open drain)

terminals; body	1.0 x 1.0 x 0.35 mm		SOT12
	$(4\times)^{(2)}$		
	terminal 1 index area		
Dimensions	0 0.5 1 mm scale		
Unit A <sup>(1)</sup>	A <sub>1</sub> b D E e e <sub>1</sub> L L <sub>1</sub>		
mm nom min	0.04         0.20         1.05         1.05         0.35         0.40           0.15         1.00         1.00         0.55         0.35         0.30         0.35           0.12         0.95         0.95         0.27         0.32		
Note 1. Including plating 2. Visible dependin	hickness. g upon used manufacturing technology.		
Outline	References	European	sot1202_p
version	IEC JEDEC JEITA	projection	Issue date
SOT1202		$\neg \phi$	<del>-10-04-02</del> -



### Low-power 2-input NAND gate (open drain)

X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals: body 0.8 x 0.8 x 0.35 mm





# 13. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

### 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP1G38 v.8	202220207	Product data sheet	-	74AUP1G38 v.7
Modifications:	<ul> <li>The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li>Fig. 10: Package outline drawing for SOT353-1 (TSSOP5) has changed.</li> <li>Type number 74AUP1G38GF (SOT891/XSON6) removed.</li> <li>Section 1 and Section 2 updated.</li> <li>Table 5: Derating values for P<sub>tot</sub> total power dissipation updated.</li> </ul>			
74AUP1G38 v.7	20160404	Product data sheet	-	74AUP1G38 v.6
Modifications:	<u>Fig. 7</u> : Typo corrected in pin naming (pins A and B swapped)			
74AUP1G38 v.6	20120628 Product data sheet - 74AUP1G38		74AUP1G38 v.5	
Modifications:	<ul> <li>Added type number 74AUP1G38GX (SOT1226)</li> <li>Package outline drawing of SOT886 (Fig. 11) modified.</li> </ul>			
74AUP1G38 v.5	20111129	Product data sheet	-	74AUP1G38 v.4
Modifications:	Legal pages updated.			
74AUP1G38 v.4	20101007	Product data sheet	-	74AUP1G38 v.3
74AUP1G38 v.3	20090622	Product data sheet	-	74AUP1G38 v.2
74AUP1G38 v.2	20070614	Product data sheet	-	74AUP1G38 v.1
74AUP1G38 v.1	20061020	Product data sheet	-	-

# 15. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

 Please consult the most recently issued document before initiating or completing a design.

- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <u>https://www.nexperia.com</u>.

#### **Definitions**

**Draft** — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. Nexperia does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local Nexperia sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

**Product specification** — The information and data provided in a Product data sheet shall define the specification of the product as agreed between Nexperia and its customer, unless Nexperia and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the Nexperia product is deemed to offer functions and qualities beyond those described in the Product data sheet.

#### **Disclaimers**

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia takes no responsibility for the content in this document if provided by an information source outside of Nexperia.

In no event shall Nexperia be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, Nexperia's aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of Nexperia.

**Right to make changes** — Nexperia reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

**Suitability for use** — Nexperia products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an Nexperia product can reasonably be expected to result in personal

#### Low-power 2-input NAND gate (open drain)

injury, death or severe property or environmental damage. Nexperia and its suppliers accept no liability for inclusion and/or use of Nexperia products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

**Quick reference data** — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

**Applications** — Applications that are described herein for any of these products are for illustrative purposes only. Nexperia makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using Nexperia products, and Nexperia accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the Nexperia product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

Nexperia does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using Nexperia products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). Nexperia does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — Nexperia products are sold subject to the general terms and conditions of commercial sale, as published at <u>http://www.nexperia.com/profile/terms</u>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. Nexperia hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of Nexperia products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

**Export control** — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Non-automotive qualified products — Unless this data sheet expressly states that this specific Nexperia product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. Nexperia accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without Nexperia's warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond Nexperia's specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies Nexperia for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond Nexperia's standard warranty and Nexperia's product specifications.

**Translations** — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

#### Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.